

RKS1500DKK

Silicon Epitaxial Planar Diode for UHF/VHF tuner Band Switch

REJ03G0400-0100 Rev.1.00 Oct 14, 2004

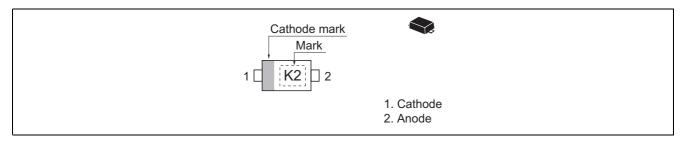
Features

- Low forward resistance. (rf = $0.7 \Omega \text{ max}$)
- Super small Flat Package (SFP) is suitable for surface mount design.

Ordering Information

| Type No. | Laser Mark | Package Code |
|------------|------------|--------------|
| RKS1500DKK | K2 | SFP |

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

| Item | Symbol | Value | Unit |
|----------------------|--------|-------------|------|
| Reverse voltage | V_R | 35 | V |
| Power dissipation | Pd | 150 | mW |
| Junction temperature | Tj | 125 | °C |
| Storage temperature | Tstg | −55 to +125 | °C |

Electrical Characteristics

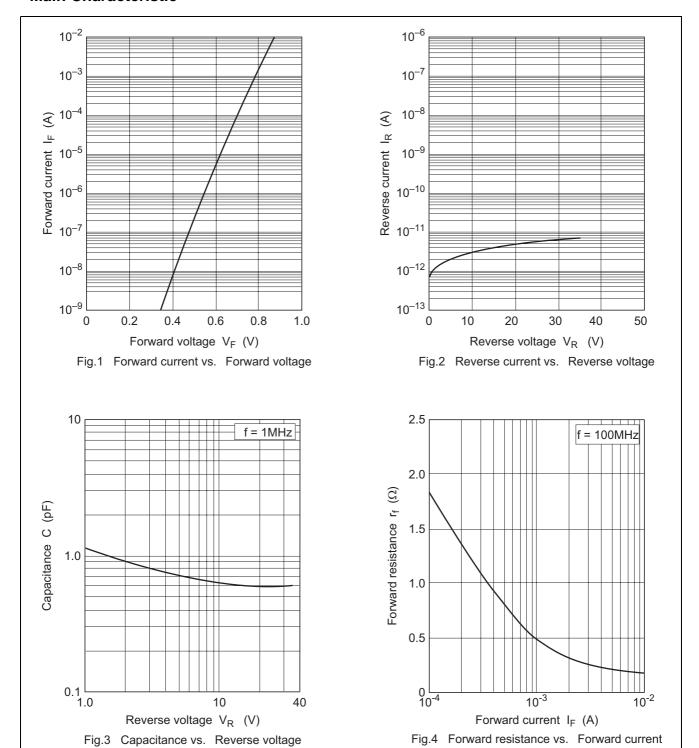
 $(Ta = 25^{\circ}C)$

| Item | Symbol | Min | Тур | Max | Unit | Test Condition |
|--------------------|----------------|-----|-----|-----|------|------------------------------------|
| Reverse current | I _R | _ | | 50 | nA | V _R = 25 V |
| Forward voltage | V_{F} | _ | _ | 1.0 | V | I _F = 10 mA |
| Capacitance | С | _ | _ | 1.2 | pF | $V_R = 6 V, f = 1 MHz$ |
| Forward resistance | r _f | _ | _ | 0.7 | Ω | I _F = 2 mA, f = 100 MHz |

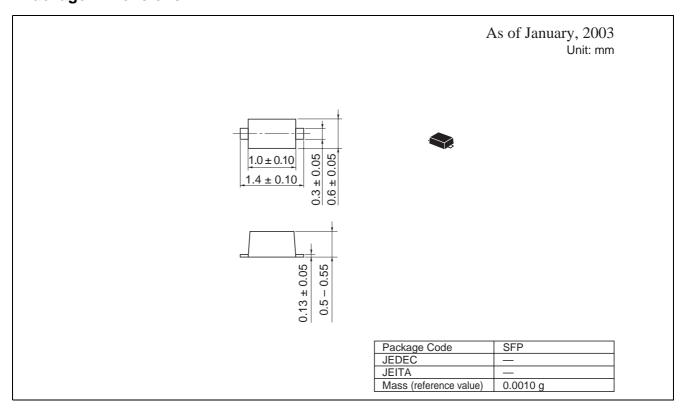
Notes: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

^{2.} The material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Main Characteristic



Package Dimensions



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